

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1.-27. (canceled).

28. (currently amended): A chip manufacturing method, said method comprising:

forming a plurality of elements on a wafer; and

arranging said plurality of elements in or more two lines on said wafer;

separating said lines with straight cutting paths;

cutting out a plurality of chips with curved cutting paths, each chip including one of the

elements from said wafer;

wherein

each element includes a substantially arcuate shape;

each chip includes a concave boundary line and a convex boundary line that substantially

follow an outline of said one of the elements, and

the concave boundary line of one chip of said plurality of chips is shaped as a common
line with the convex boundary line of another chip of said plurality of chips that adjoined said
one chip on said wafer.

29. (original): The chip manufacturing method as claimed in claim 28, wherein said

chips are cut from said wafer using laser beam.

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30. (original): The chip manufacturing method as claimed in claim 28, wherein said chips are cut from said wafer using an ultrasonic vibration tool.

31. (original): The chip manufacturing method as claimed in claim 28, wherein said chips are cut from said wafer using hydraulic pressure.

32. (original): The chip manufacturing method as claimed in claim 28, wherein dicing is used to cut the straight-line portions of the contours of said elements.

33. (original): The chip manufacturing method as claimed in claim 28, further comprising mounting a plate on at least a portion of said chip.

34. (currently amended): A chip manufacturing method, said method comprising:
forming a plurality of elements on a wafer;
arranging said plurality of elements in two or more lines on said wafer;
separating said lines with straight cutting paths;
cutting out a plurality of first chips with curved cutting paths, each first chip including one of said elements;
cutting out a second chip having a contour that is substantially similar to the contour of said first chip; and
bonding one of said first chips to said second chip;

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wherein

each element includes a substantially arcuate shape,

each of said first chips includes a concave boundary line and a convex boundary line that substantially follow an outline of said one of the elements, and

wherein the concave boundary line of said one first chip of said first chips is shaped as a common line with the same as the convex boundary line of another chip of said first chips that adjoined said one first chip on said wafer.

35. (original): The chip manufacturing method as claimed in claim 34, wherein said first chip and said second chip are bonded together using an adhesive.

36. (original): The chip manufacturing method as claimed in claim 34, wherein:
said first chip is cut from a first wafer; and
said second chip is cut from a second wafer.